## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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pplication of:

Chad A. Cobbley et al.

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STACKED DIE MODULE AND

TECHNIQUES FOR FORMING A

STACKED DIE MODULE

Group Art Unit:

2813

Examiner:

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CERTIFICATE OF TRANSMISSION OR MAILING 37 C.F.R. 1.8

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December 8, 2004

Date

Sir:

## RESPONSE

In response to the Official Action mailed on September 08, 2004, Applicants respectfully request reconsideration of the above-identified application in view of the remarks set forth below.